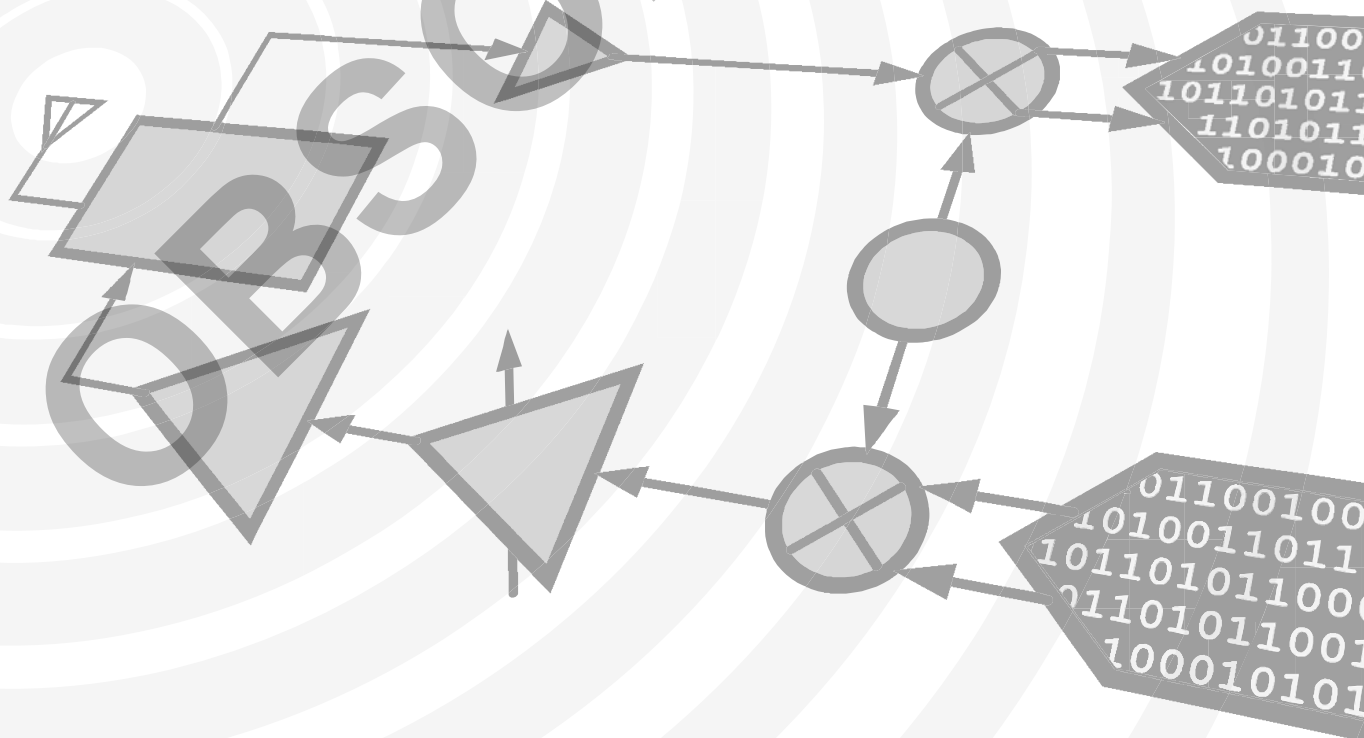




Hittite
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OBSOLETE



MICROWAVE CORPORATION v03.0309



HMC593LP3 / 593LP3E

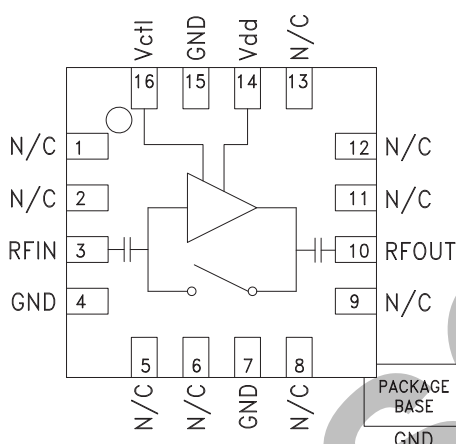
GaAs PHEMT MMIC LOW NOISE AMPLIFIER w/ BYPASS MODE, 3.3 - 3.8 GHz

Typical Applications

The HMC593LP3(E) is ideal for:

- Wireless Infrastructure
- Fixed Wireless
- WiMAX WiBro / 4G
- Tower Mounted Amplifiers

Functional Diagram



Features

Noise Figure: 1.2 dB

Output IP3: +29 dBm

Gain: 19 dB

Low Loss LNA Bypass Path

Single Supply: +3V or +5V

50 Ohm Matched Output

General Description

The HMC593LP3(E) is a versatile, high dynamic range GaAs MMIC Low Noise Amplifier that integrates a low loss LNA bypass mode on the IC. The amplifier is ideal for WiBro & WiMAX receivers operating between 3.3 and 3.8 GHz and provides 1.2 dB noise figure, 19 dB of gain and +29 dBm IP3 from a single supply of +5V @ 40mA. Input and output return losses are 23 and 13 dB respectively with no external matching components required. A single control line (0/Vdd) is used to switch between LNA mode and a low 2 dB loss bypass mode reducing the current consumption to 10 μ A.

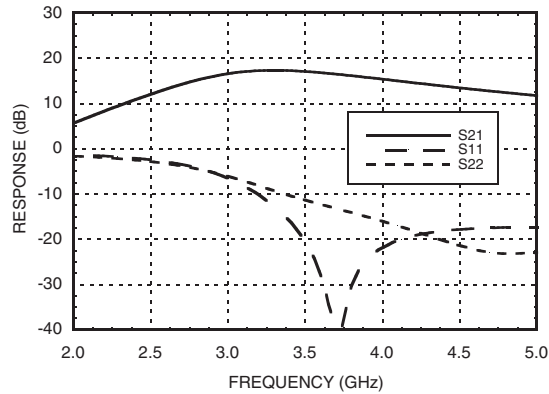
Electrical Specifications, $T_A = +25^\circ\text{C}$

Parameter		Vdd = +3V						Vdd = +5V						Units
		LNA Mode			Bypass Mode			LNA Mode			Bypass Mode			
		Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency Range		3.3 - 3.8												GHz
Gain		14	17		-3	-2		16	19		-3	-2		dB
Gain Variation Over Temperature			0.011			0.002			0.011			0.002		dB / °C
Noise Figure			1.4	1.8					1.2	1.6				dB
Input Return Loss			23			30			23			30		dB
Output Return Loss			12			25			13			25		dB
Reverse Isolation			39						36					dB
Power for 1dB Compression (P1dB)*		10	13			30		13	16			30		dBm
Saturated Output Power (Psat)			13.5						17					dBm
Third Order Intercept (IP3)* (-20 dBm Input Power per tone, 1 MHz tone spacing)			22						29					dBm
Supply Current (Idd)			20	25		0.01			40	50		0.01		mA
Switching Speed	LNA Mode to Bypass Mode		428						428					ns
	Bypass Mode to LNA Mode					343						343		ns

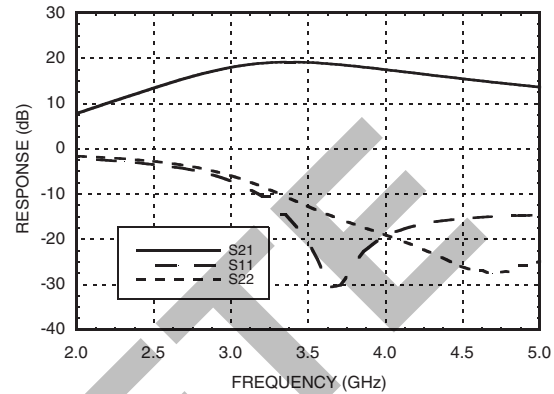
* P1dB and IP3 for LNA Mode are referenced to RFOUT while P1dB for Bypass Mode is referenced to RFIN.

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com

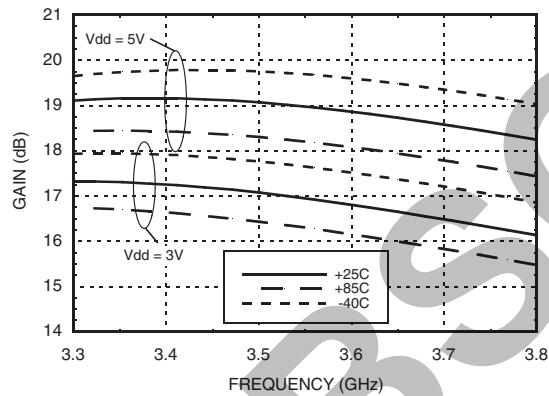
**LNA Broadband Gain
& Return Loss @ Vdd= 3V**



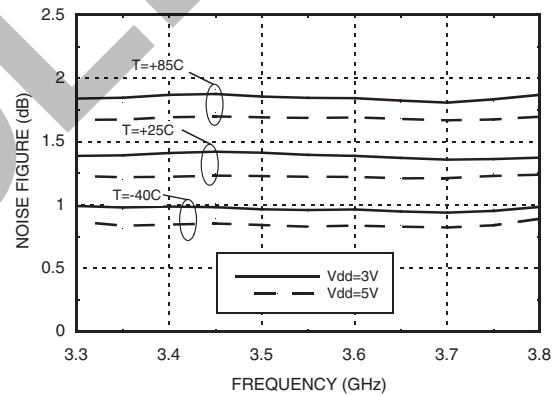
**LNA Broadband Gain
& Return Loss @ Vdd= 5V**



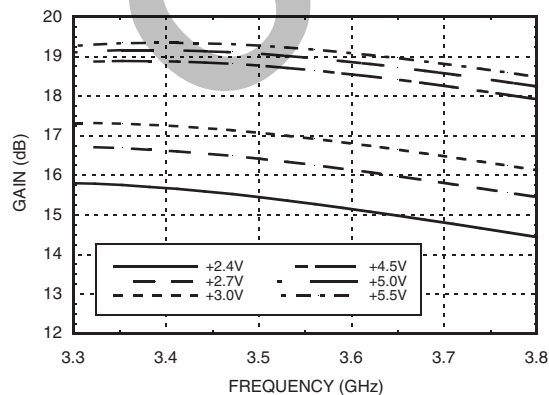
LNA Gain vs. Temperature



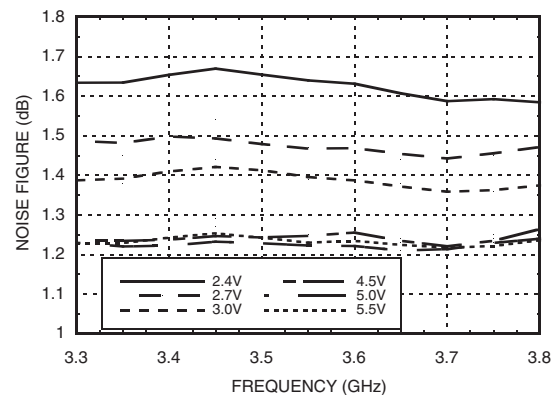
LNA Noise Figure vs. Temperature



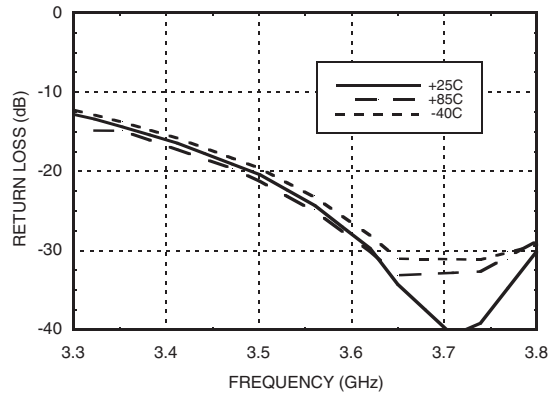
LNA Gain vs. Vdd



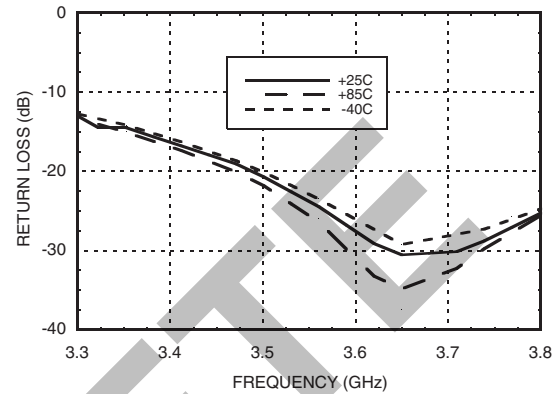
LNA Noise Figure vs. Vdd



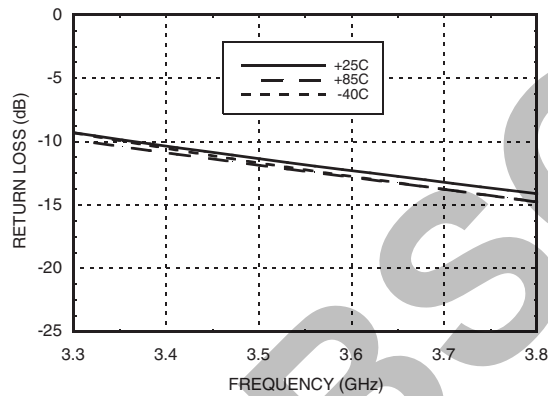
**LNA Input Return Loss
vs. Temperature @ Vdd= 3V**



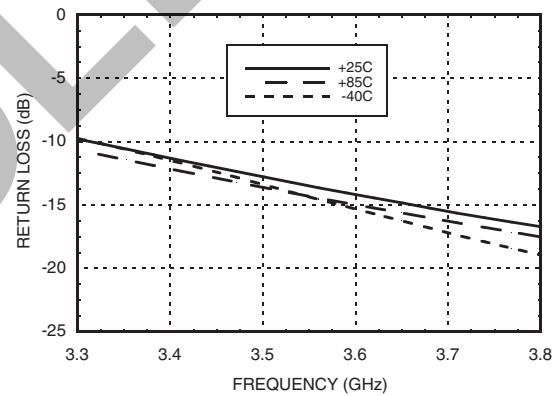
**LNA Input Return Loss
vs. Temperature @ Vdd= 5V**



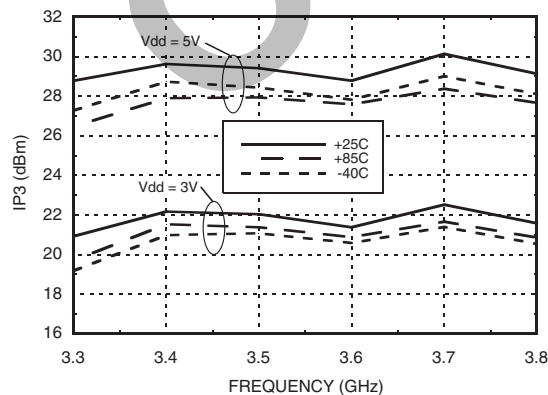
**LNA Output Return Loss
vs. Temperature @ Vdd= 3V**



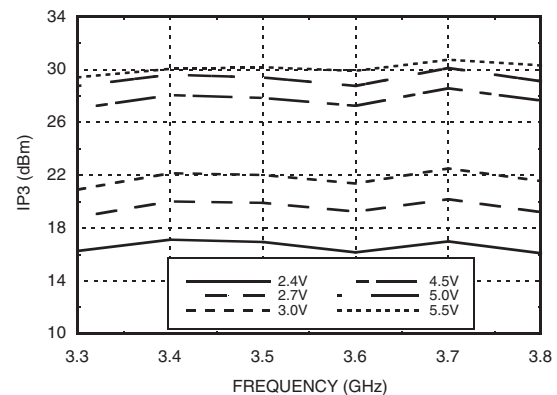
**LNA Output Return Loss
vs. Temperature @ Vdd= 5V**



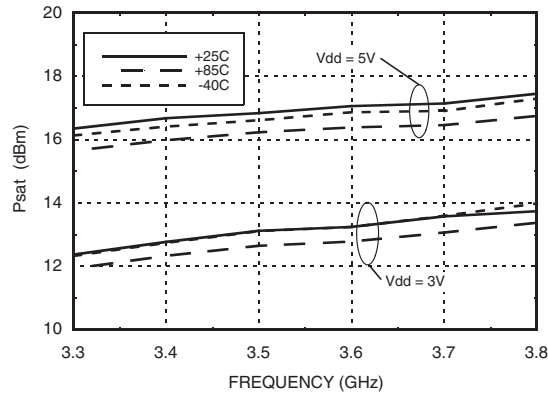
LNA Output IP3 vs. Temperature



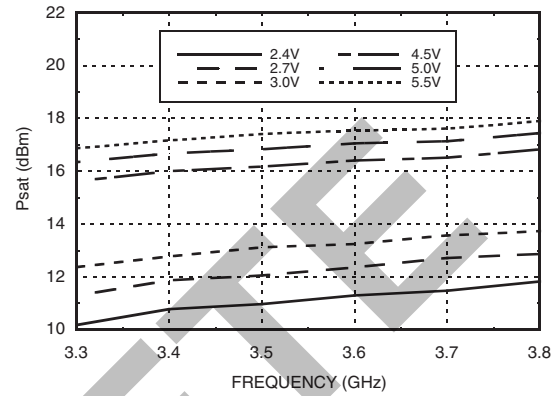
LNA Output IP3 vs. Vdd



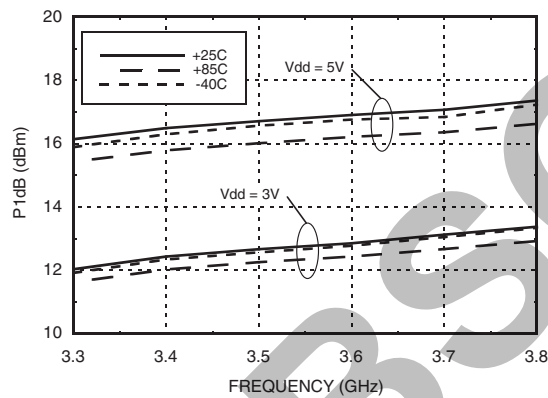
LNA Psat vs. Temperature



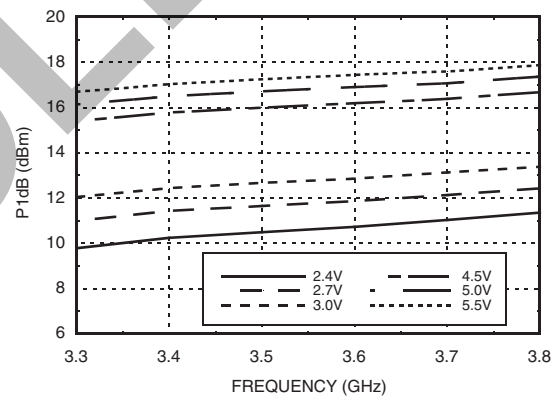
LNA Psat vs. Vdd



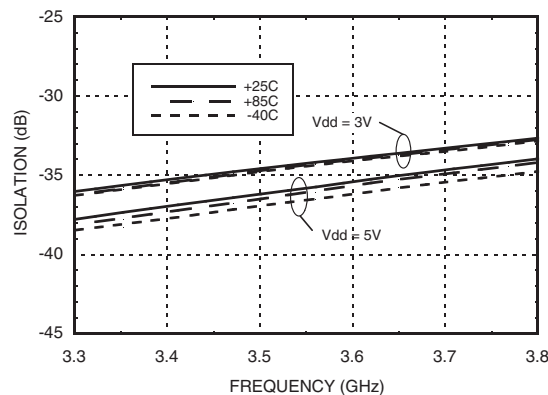
LNA Output P1dB vs. Temperature



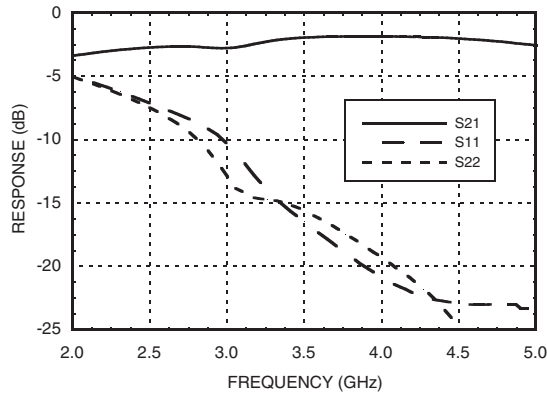
LNA Output P1dB vs. Vdd



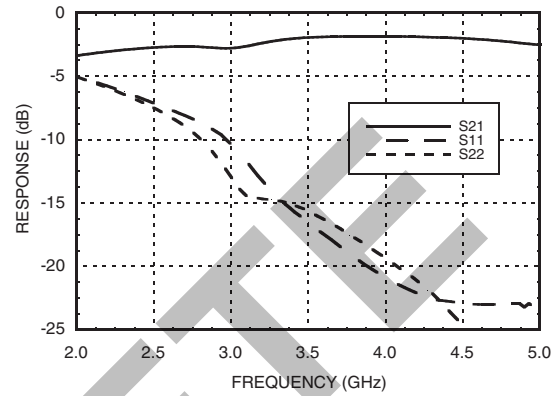
LNA Reverse Isolation vs. Temperature



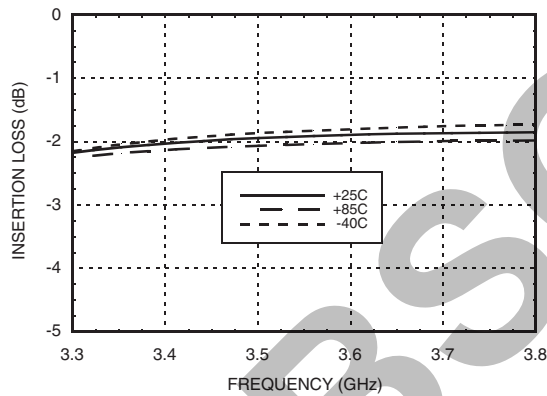
**Bypass Mode
Broadband Gain & Return Loss [1]**



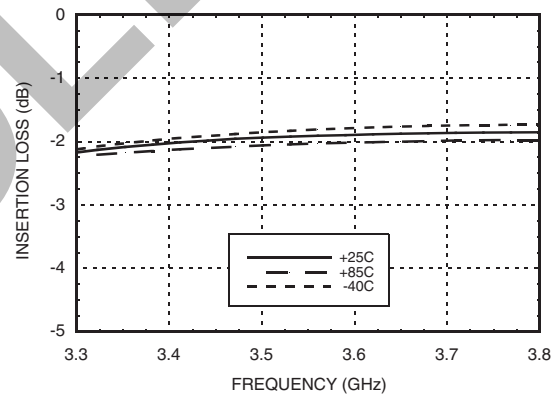
**Bypass Mode
Broadband Gain & Return Loss [2]**



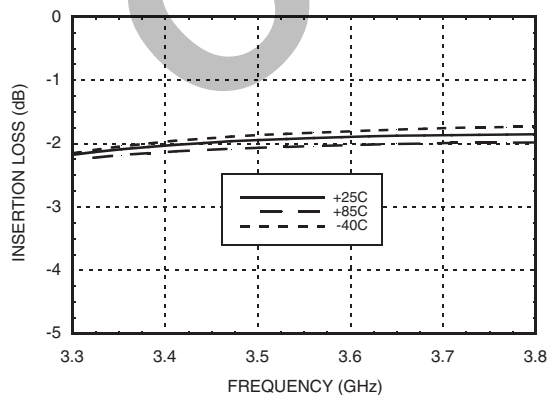
**Bypass Mode
Insertion Loss vs. Temperature [1]**



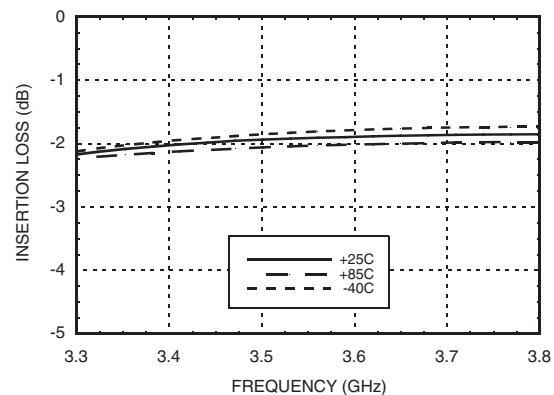
**Bypass Mode
Insertion Loss vs. Temperature [2]**



Bypass Mode, Input IP3 vs. Temperature

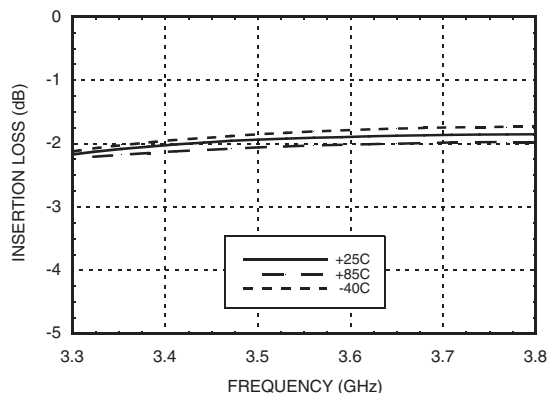


Bypass Mode, P1dB vs. Temperature



[1] Vdd = 3V [2] Vdd = 5V

Bypass Mode, Psat vs. Temperature



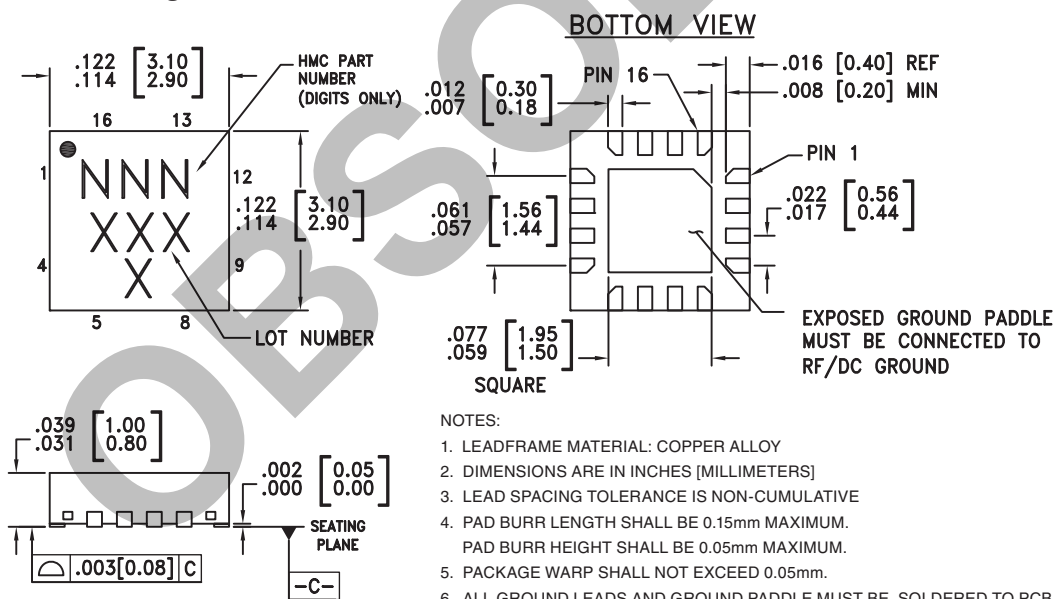
Typical Supply Current vs. Vdd

Vdd (V)	Idd (mA)
+2.4	9
+2.7	12
+3.0	16
+4.5	33
+5.0	39
+5.5	44

Absolute Maximum Ratings

Drain Bias Voltage (Vdd)	+8 V
RF Input Power (RFIN) (Vdd = +5.0 Vdc)	LNA Mode +15 dBm Bypass Mode +30 dBm
Channel Temperature	150 °C
Continuous P _{diss} (T = 85 °C) (derate 13 mW/°C above 85 °C)	850 mW
Thermal Resistance (channel to ground paddle)	76.9 °C/W
Storage Temperature	-65 to +150° C
Operating Temperature	-40 to +85° C
ESD Sensitivity (HBM)	Class 1A

Outline Drawing



Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC593LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	593 XXXX
HMC593LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	593 XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX



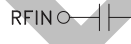
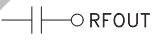
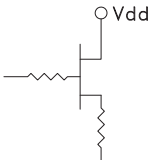
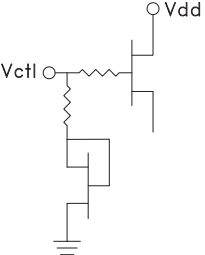
Truth Table

LNA Mode	Vctl = Vdd
Bypass Mode	Vctl = 0V



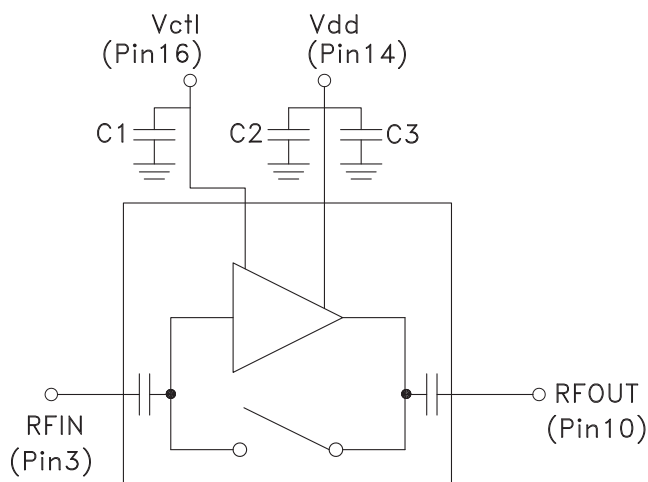
ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

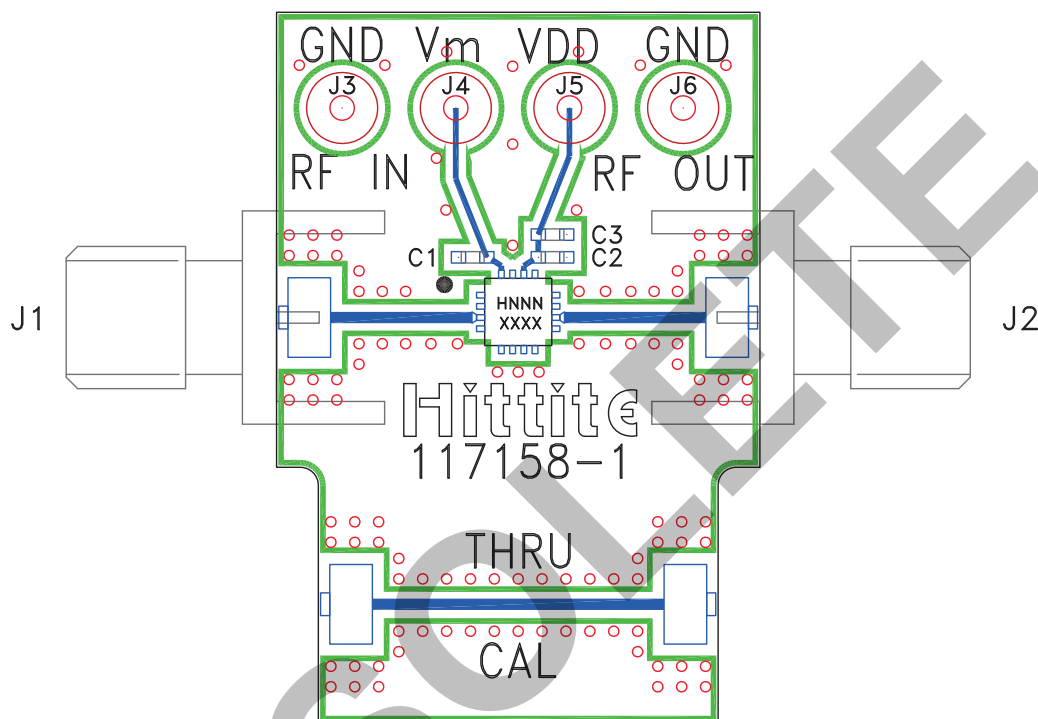
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 2, 5, 6, 8, 9, 11 - 13	N/C	No connection necessary. These pins may be connected to RF/DC ground.	
3	RFIN	This pin is AC coupled and matched to 50 Ohms.	
4, 7, 15	GND	These pins must be connected to RF/DC ground.	
10	RFOUT	This pin is AC coupled and matched to 50 Ohms.	
14	Vdd	Power supply voltage. Bypass capacitors are required. See application circuit.	
16	Vctl	LNA/Bypass Mode Control Voltage. See truth table.	

Application Circuit

Component	Value
C1, C2	100pF
C3	10KpF



Evaluation PCB

List of Materials for Evaluation PCB 117160 ^[1]

Item	Description
J1 - J2	PCB Mount SMA RF Connector
J3 - J6	DC Pin
C1, C2	100 pF Capacitor, 0402 Pkg.
C3	10 KpF Capacitor, 0402 Pkg.
U1	HMC593LP3 / HMC593LP3E Amplifier
PCB ^[2]	117158 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350 or Arlon 25FR

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.